



Product Change Notification

Change Notification #: 114799 - 00
Change Title: Intel® Server System R2208WTTYSR
PCN114799 – 00,
Product Design, DIMM connector change
Date of Publication: August 05, 2016

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material *:	August 08, 2016
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the Intel® Server System R2208WTTYSR:

- Replaced dual in-line memory module (DIMM) connectors to increase gold plating thickness from 15u” to 30u” for higher durability

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA	Pre PBA	Post PBA
R2208WTTYSR	943826	J11484-003	J11484-004	G92187-366	G92187-367

PCN Revision History:

Date of Revision: August 05, 2016	Revision Number: 00	Reason: Originally Published PCN
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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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